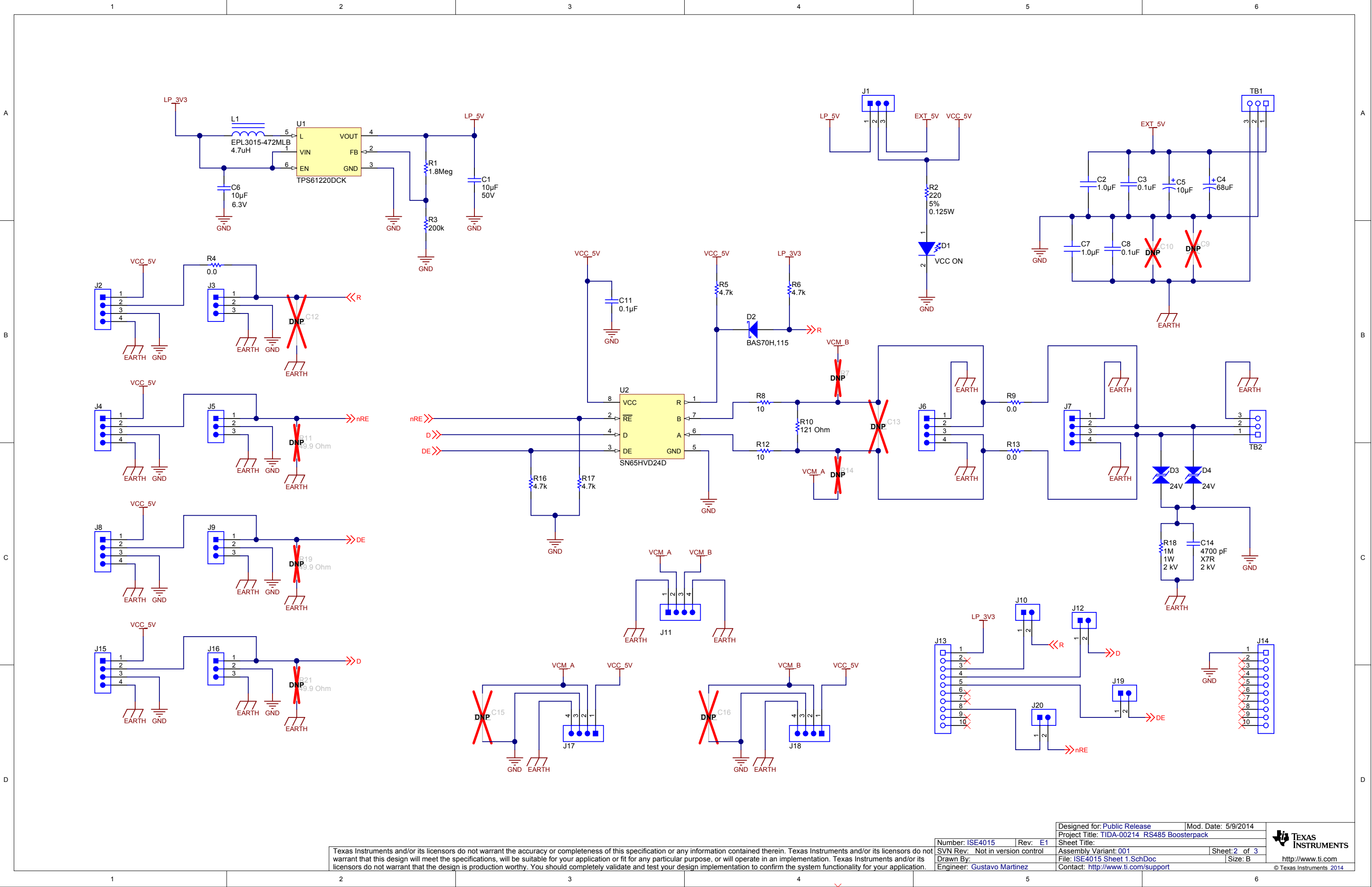


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Sheet Title:				
SVN Rev: Not in version control		Assembly Variant: 001		
Drawn By:		File: ISE4015 Cover Sheet.SchDoc		Sheet: 1 of 3
Engineer: Gustavo Martinez		Contact: http://www.ti.com/support		Size: B
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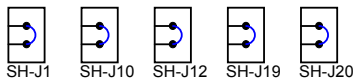
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PCB Number: ISE4015
PCB Rev: E1

PCB
LOGO
Texas Instruments



B

B

C

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ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Project Title: TIDA-00214 RS485 Boosterpack					
Sheet Title:					
SVN Rev: Not in version control			Assembly Variant: 001	Sheet: 3 of 3	
Drawn By:			File: ISE4015 E1 Hdw.SchDoc	Size: B	
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